

• General Description

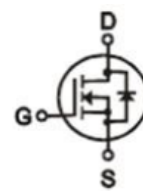
The ZM027N03I combines advanced trench MOSFET technology with a low resistance package to provide extremely low $R_{DS(ON)}$. This device is ideal for load switch and battery protection applications.

• Features

- Advance high cell density Trench technology
- Low $R_{DS(ON)}$ to minimize conductive loss
- Low Gate Charge for fast switching
- Low Thermal resistance

• Application

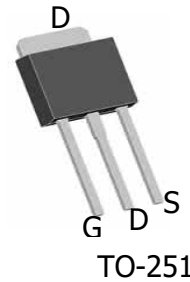
- MB/VGA Vcore
- SMPS 2nd Synchronous Rectifier
- POL application
- BLDC Motor driver

• Product Summary


$V_{DS} = 30V$

$R_{DS(ON)} = 2.7m\Omega$

$I_D = 95A$


• Ordering Information:

Part NO.	ZM027N03I
Marking	ZM027N03
Packing Information	REEL TAPE
Basic ordering unit (pcs)	900

• Absolute Maximum Ratings ($T_C = 25^\circ C$)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DS}	30	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current	$I_D @ TC=25^\circ C$	95	A
	$I_D @ TC=75^\circ C$	72	A
	$I_D @ TC=100^\circ C$	60	A
Pulsed Drain Current ^①	I_{DM}	220	A
Total Power Dissipation	$P_D @ TC=25^\circ C$	70	W
Total Power Dissipation	$P_D @ TA=25^\circ C$	2.8	W
Operating Junction Temperature	T_J	-55 to 175	$^\circ C$
Storage Temperature	T_{STG}	-55 to 175	$^\circ C$
Single Pulse Avalanche Energy ($L=0.5mH, V_{GS}=10V, R_g=25\Omega, T_J=25^\circ C$)	E_{AS}	350	mJ



Single Pulse Avalanche Energy ($L=0.1\text{mH}$, $V_{GS}=10\text{V}$, $R_g=25\Omega$, $T_J=25^\circ\text{C}$)	E_{AS}	180	mJ
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Thermal resistance

Parameter	Symbol	Min.	Typ.	Max.	Unit
Thermal resistance, junction - case	R_{thJC}	-	-	1.8	$^\circ\text{C/W}$
Thermal resistance, junction - ambient	R_{thJA}	-	-	45	$^\circ\text{C/W}$
Soldering temperature, wave soldering for 10s	T_{sold}	-	-	265	$^\circ\text{C}$

Electronic Characteristics

Parameter	Symbol	Condition	Min.	Typ	Max.	Unit
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0\text{V}$, $I_D=250\mu\text{A}$	30			V
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{GS}=V_{DS}$, $I_D=250\mu\text{A}$	1.2		2.5	V
Drain-Source Leakage Current	I_{DSS}	$V_{DS}=30\text{V}$, $V_{GS}=0\text{V}$			1.0	μA
Gate- Source Leakage Current	I_{GSS}	$V_{GS}=\pm 20\text{V}$, $V_{DS}=0\text{V}$			± 100	nA
Static Drain-source On Resistance	$R_{DS(ON)}$	$V_{GS}=10\text{V}$, $I_D=24\text{A}$		2.7	3.6	m Ω
		$V_{GS}=4.5\text{V}$, $I_D=12\text{A}$		4.6	5.5	m Ω
Forward Transconductance	g_{FS}	$V_{DS}=25\text{V}$, $I_D=10\text{A}$		30		s
Source-drain voltage	V_{SD}	$I_S=24\text{A}$			1.28	V

Electronic Characteristics

Parameter	Symbol	Condition	Min.	Typ	Max.	Unit
Input capacitance	C_{iss}	$f = 1\text{MHz}$, $V_{DS}=25\text{V}$	-	2800	-	μF
Output capacitance	C_{oss}		-	420	-	
Reverse transfer capacitance	C_{rss}		-	280	-	

Gate Charge characteristics ($T_a = 25^\circ\text{C}$)

Parameter	Symbol	Condition	Min.	Typ	Max.	Unit
Gate Resistance	R_g	$f = 1\text{MHz}$		2.5		Ω
Total gate charge	Q_g	$V_{DD} = 25\text{V}$ $I_D = 8\text{A}$ $V_{GS} = 10\text{V}$	-	27	-	nC
Gate - Source charge	Q_{gs}		-	8.6	-	
Gate - Drain charge	Q_{gd}		-	13.8	-	

Turn-ON Delay time	$t_{D(on)}$	$V_{GS}=10V, V_{DS}=15V$ $R_G = 3.3\Omega, I_D = 15A$	12	ns
Turn-ON Rise time	t_r		44	ns
Turn-Off Delay time	$t_{D(off)}$		50	ns
Turn-Off Fall time	t_f		15	ns
Reverse Recovery Time	t_{RR}	$V_{DD} = 20V,$ $dI_S/dt = 100 A/s,$ $I_S = 30 A$	5.8	ns
Charge Time	t_a		3.4	ns
Discharge Time	t_b		2.4	ns
Reverse Recovery Charge	Q_{RR}		1.6	nC

Note: ① Pulse Test : Pulse width $\leq 300\mu s$, Duty cycle $\leq 2\%$;

Fig.1 Power Dissipation

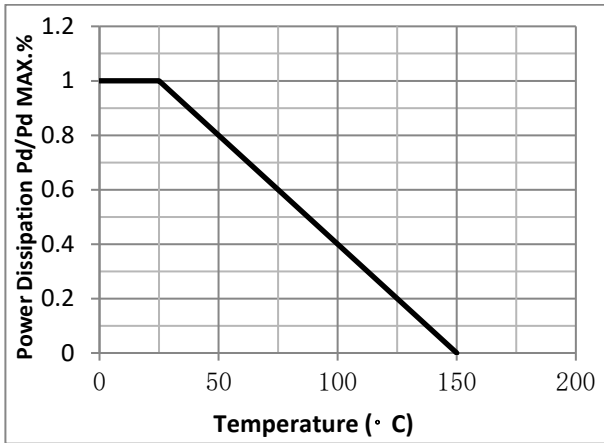


Fig.2 Typical output Characteristics

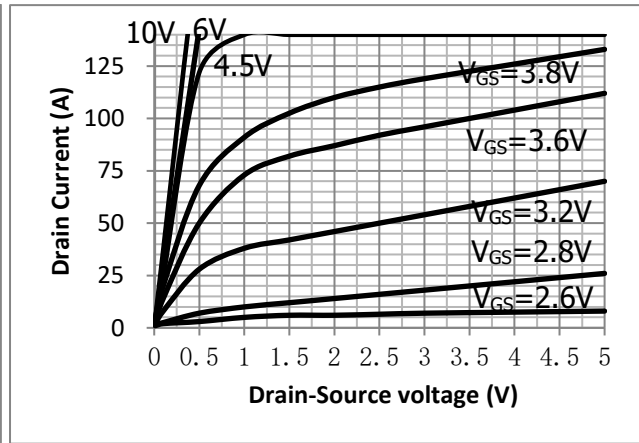


Fig.3 Threshold Voltage V.S Junction Temperature

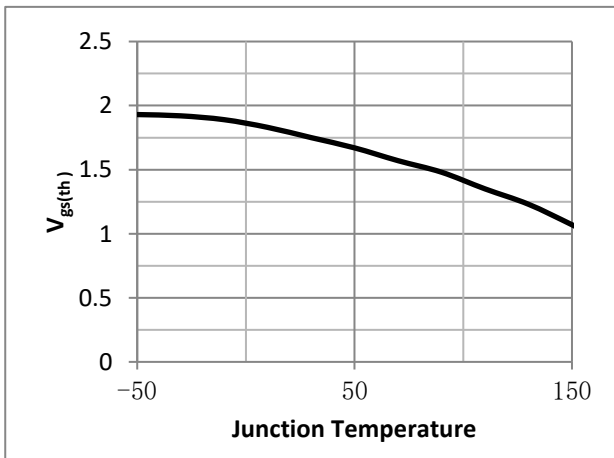


Fig.4 Resistance V.S Drain Current

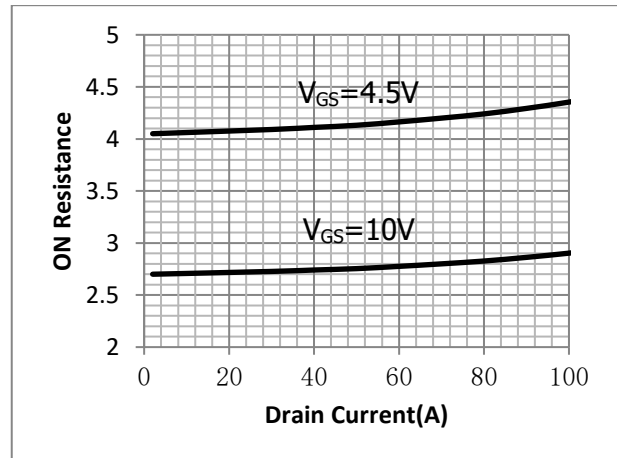


Fig.5 On-Resistance VS Gate Source Voltage

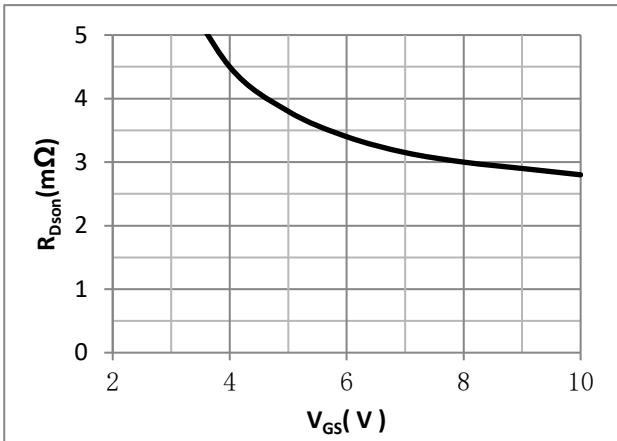


Fig.6 On-Resistance V.S Junction Temperature

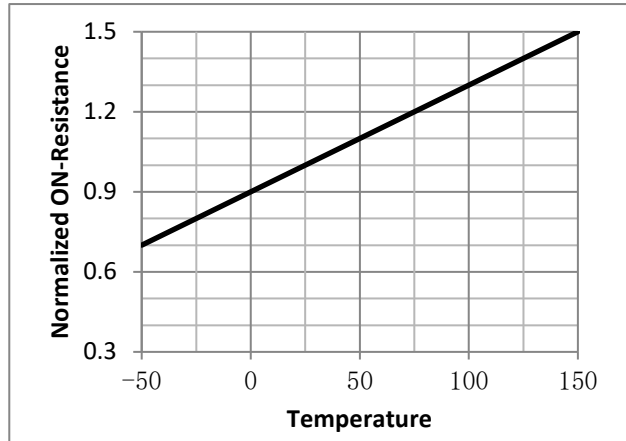


Fig.7 SOA Maximum Safe Operating Area

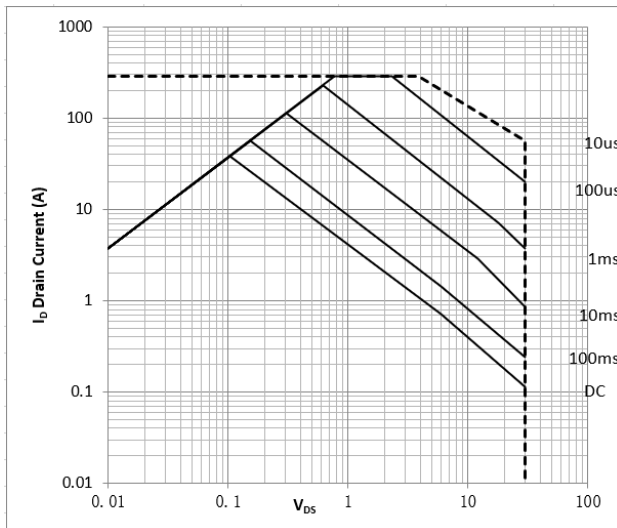


Fig.8 ID-Junction Temperature

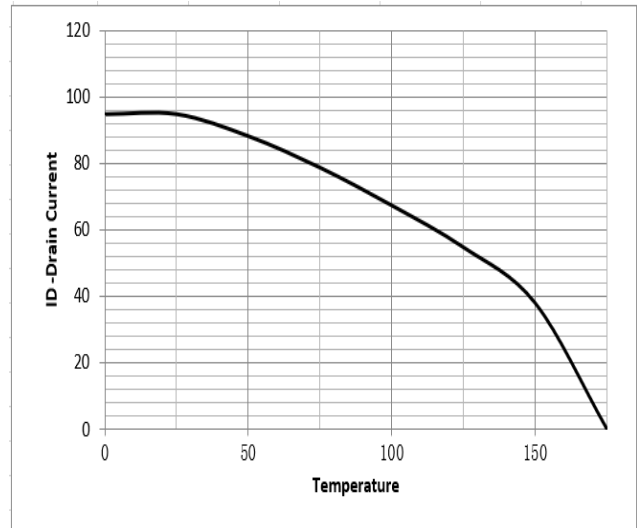


Figure 9. Diode Forward Voltage vs. Current

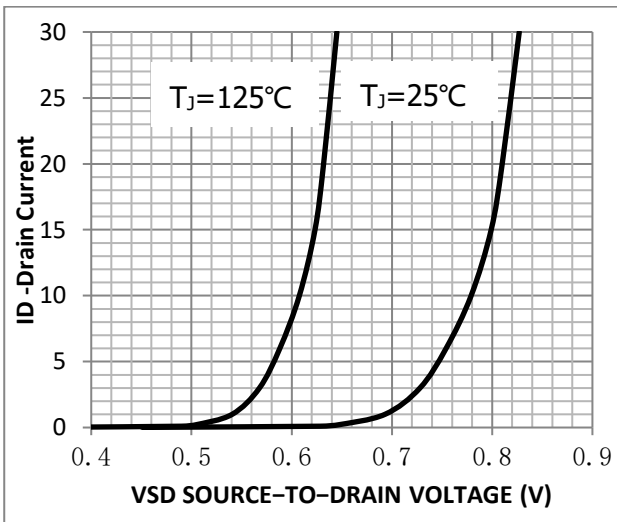


Figure 10. Transfer Characteristics

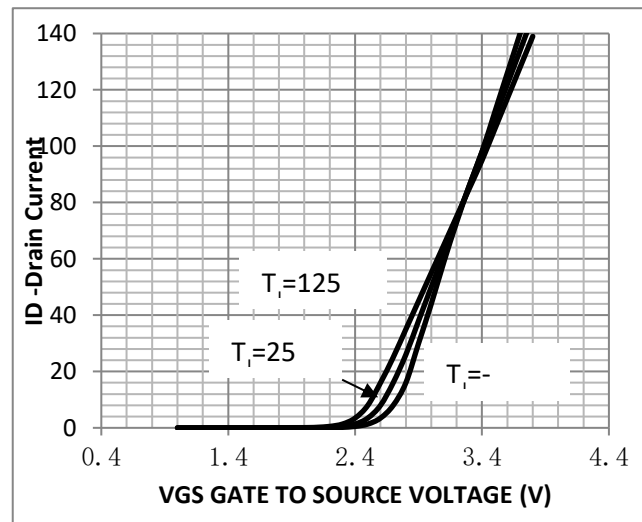


Figure 11. Gate-to-Source and Drain-to-Source Voltage vs. Total Charge

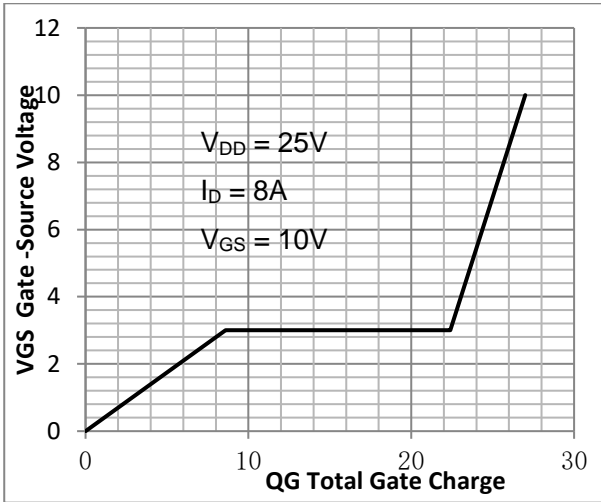


Fig.12 Capacitance Variation

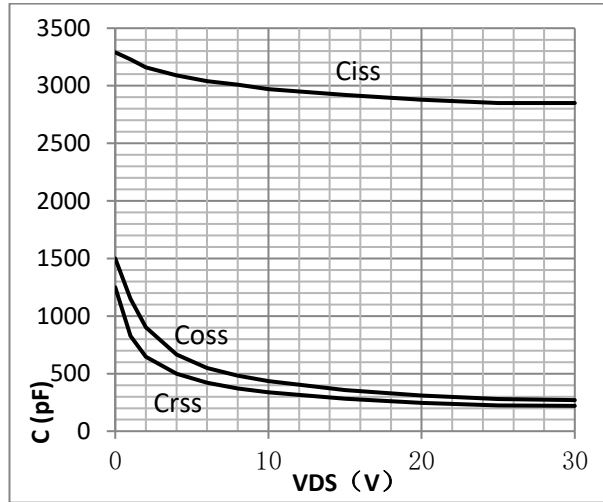


Fig.13 Switching Time Measurement Circuit

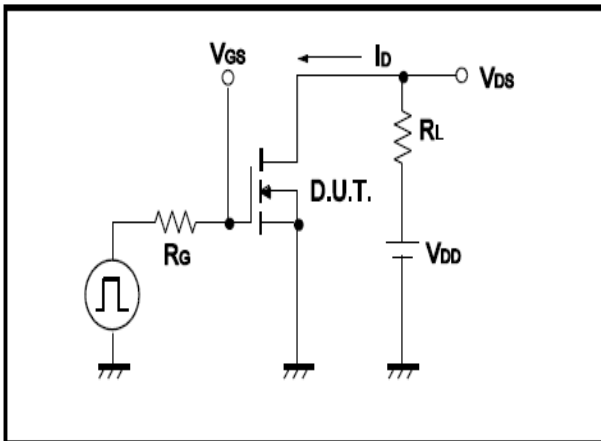


Fig.14 Gate Charge Waveform

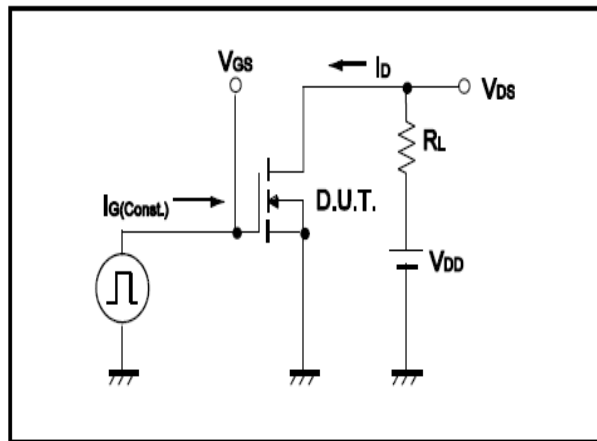


Fig.15 Avalanche Measurement Circuit

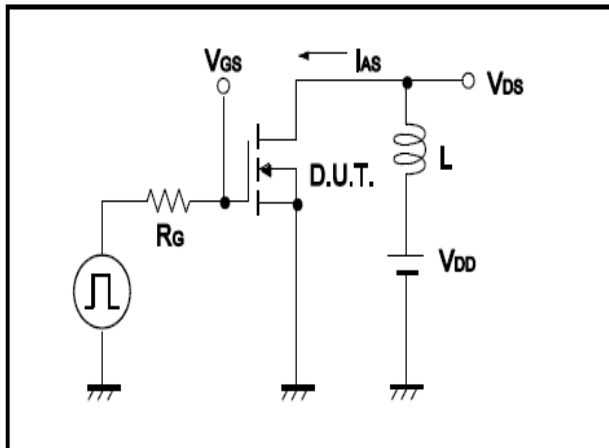


Fig.16 Avalanche Waveform

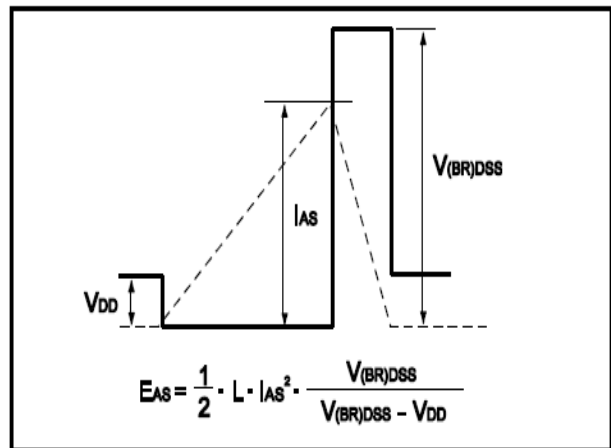
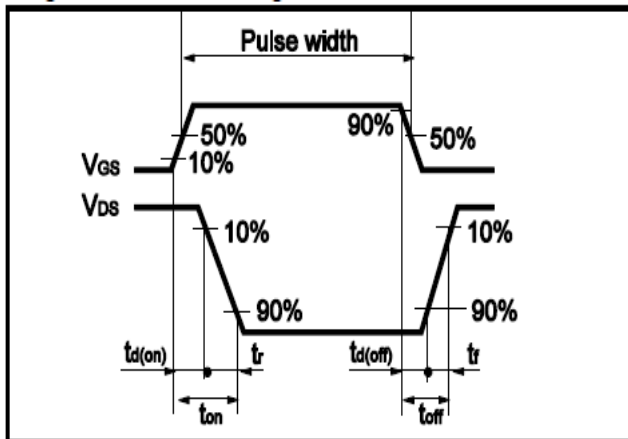


Fig.17 Gate Charge Waveform





•Dimensions(TO-251)

Unit: mm

SYMBOL	min	max	SYMBOL	min	max
A	2.10	2.50	D	6.35	6.80
A1	0.95	1.30	D1	5.10	5.50
B	0.80	1.25	E	5.30	6.30
b	0.50	0.80	e	2.24	2.35
b1	0.70	0.90	E1	4.43	4.73
c	0.45	0.60	L	7.00	9.40
c1	0.45	0.60			

